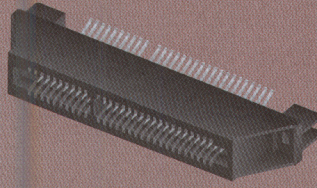
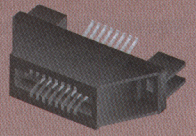
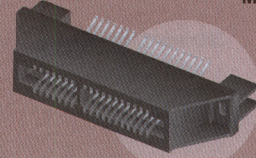




MEC1-130-02-S-D-EM1



MEC1-108-02-L-D-EM2-NP



MEC1-120-02-F-D-EM1

MINI EDGE-CARD SOCKET MEC1-EM SERIES

SPECIFICATIONS

For complete specifications see www.samtec.com?MEC1-EM

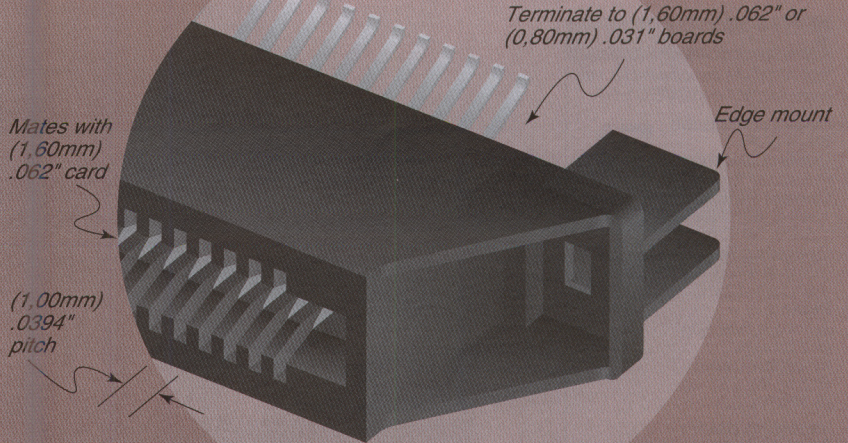
Insulator Material: Black LCP
Contact Material: Phosphor Bronze
Current Rating: Testing Now!



Operating Temp Range: -65°C to +105°C with Tin; -65°C to +125°C with Gold

Plating: Au or Sn over 50µ" (1,27µm) Ni
Insertion Depth: (5,84mm) .230" to (8,13mm) .320"

Mates with: (1,60mm) .062" card

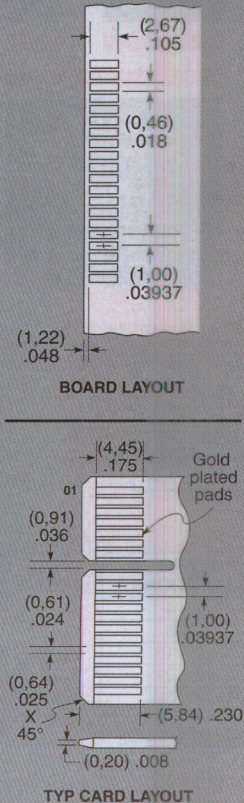


Important Note: Samtec recommends that pads on the mating board be Gold plated.

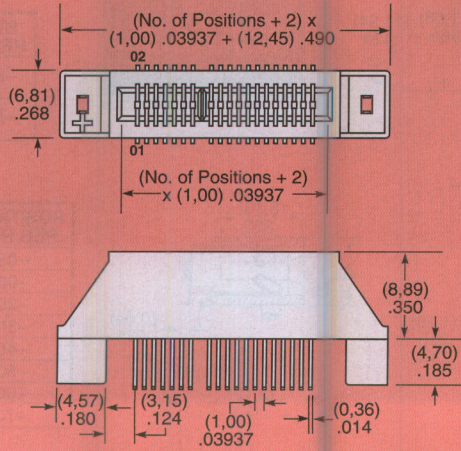
Note: Some sizes, styles and options are non-standard, non-returnable.

Processing:

Max Processing Temp: 230°C for 60 seconds
Suggested PCB Layouts: For reference only. Please contact Samtec or go to www.samtec.com?MEC1-EM for recommended PCB layout.

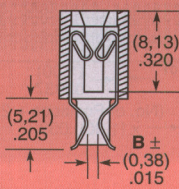


MEC1	1	POSITIONS PER ROW	02	PLATING OPTION	D	PCB OPTION	OTHER OPTION
		05, 08, 20, 30, 40, 50, 60, 70		-F = Gold flash on contact, Tin on tail -L = 10µ" (0,25µm) Gold on contact, Tin on tail -S = 30µ" (0,76µm) Gold on contact, Tin on tail		-EM1 = (0,80mm) .031 thick PCB -EM2 = (1,60mm) .062 thick PCB	Leave blank for polarized version -NP = Non-polarized (05, 08, 20 & 30 positions/row only)



PCB OPTION	B
-EM1	(0,41) .016
-EM2	(1,19) .047

POSITIONS PER ROW	POLARIZED POSITIONS
-05	3, 4
-08	5, 6
-20	15, 16
-30	21, 22
-40	31, 32
-50	41, 42
-60	31, 32, 63 & 64
-70	53, 54, 115 & 116



Due to technical progress, all designs, specifications and components are subject to change without notice.

WWW.SAMTEC.COM